

Electronic Patent Application Fee Transmittal

Application Number:	10588473			
Filing Date:	01-Aug-2006			
Title of Invention:	Optimized Contact Design for Thermosonic Bonding of Flip-Chip Devices			
First Named Inventor/Applicant Name:	Ivan Eliashevich			
Filer:	Robert Michael Sieg/Mary Ann Temesvari			
Attorney Docket Number:	GLOZ 2 00201			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	490	490

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Total in USD (\$)				490